IPC ASSOCIATION CONNE	© Copyright 2005. I	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier Info	rmation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-05				
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized Repi	resentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requ	ester Item Number			Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	W	eight*	UOM	Unit Type
				FET 100V 37.0 mO	Ohm PQFN33		2024-05-05)24-05-05 PBB		20	5.798819	mg	Each	
T	ng Proccess Informa						1		·					
2 2			Cerminal Base Alloy J-STD-020 MS		Rating	Peak Process Body Temperatu		•				er of Reflow Cyc	eles	
•	Tin (Sn) - annealed	C	U Alloy	1			260		С	30	second	s 3		
omments														
	m time at peak temperatu													
r more inform	ation regarding material	composition]	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier sate as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.131732	mg	Supplier	Silicon (Si)	7440-21-3		0.1317	mg
Die Attach Solder	1.42008	mg	Supplier	Silver (Ag)	7440-22-4		0.0355	mg
			A	Lead (Pb)	7439-92-1	7a	1.3136	mg
			Supplier	Tin (Sn)	7440-31-5		0.071	mg
Lead Frame	11.0676	mg	Supplier	Silver (Ag)	7440-22-4		0.5534	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0133	mg
			Supplier	Iron (Fe)	7439-89-6		0.2656	mg
			Supplier	Copper (Cu)	7440-50-8		10.2264	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0089	mg
Mold Compound-Black	13.1485	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.8547	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0657	mg
			Supplier	Silica (SiO2)	14464-46-1		11.5707	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6574	mg
Plating	0.476447	mg	Supplier	Tin (Sn)	7440-31-5		0.4764	mg
Wire Bond - Cu	0.554459	mg	Supplier	Palladium (Pd)	7440-05-3		0.0111	mg
			Supplier	Copper (Cu)	7440-50-8		0.5434	mg